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(54) Title (EN): ELECTRONIC DEVICE HAVING CIRCUIT STRUCTURE HAVING ELECTRIC CONNECTION BETWEEN DESIGNATED PIN INCLUDED IN CONNECTOR ELECTRICALLY CONNECTABLE TO GROUND TERMINAL OF EXTERNAL MICROPHONE AND DESIGNATED GROUND OF CIRCUIT BOARD

(54) Title (FR): DISPOSITIF ÉLECTRONIQUE DOTÉ D'UNE STRUCTURE DE CIRCUIT AYANT UNE CONNEXION ÉLECTRIQUE ENTRE UNE BROCHE DÉSIGNÉE INCLUSE DANS UN CONNECTEUR POUVANT ÊTRE CONNECTÉ ÉLECTRIQUEMENT À UNE BORNE DE MASSE D'UN MICROPHONE EXTERNE ET UNE MASSE DÉSIGNÉE D'UNE CARTE DE CIRCUIT IMPRIMÉ

(54) Title (KO): 외부 마이크로폰의 그라운드 단자와 전기적으로 연결될 수 있는 커넥터에 포함된 지정된 핀이 회로 기판의 지정된 그라운드와 전기적으로 연결된 회로 구조를 갖는 전자 장치

(57) Abstract:

(EN): Various embodiments of the present invention comprise: a circuit board comprising a first grounding portion and a second grounding portion; a wireless communication circuit arranged in a first area of the circuit board, the wireless communication circuit comprising a first grounding terminal electrically connected to the first grounding portion; an audio codec circuit arranged in a second area of the circuit board, the audio codec circuit comprising a signal input terminal and a second grounding terminal electrically connected to the second grounding portion; and a connector electrically connected to the input terminal, the connector comprising a first pin that can be electrically connected to a signal terminal of a microphone included in an external electronic device and a second pin that can be electrically connected to a grounding terminal of the microphone, the second pin being electrically connectable to the second grounding portion. In addition, various other embodiments of the present invention may be possible.

(FR): Divers modes de réalisation de la présente invention comprennent : une carte de circuit imprimé comprenant une première partie de mise à la masse et une seconde partie de mise à la terre; un circuit de communication sans fil agencé dans une première zone de la carte de circuit imprimé, le circuit de communication sans fil comprenant une première borne de mise à la masse

connectée électriquement à la première partie de mise à la masse; un circuit codec audio agencé dans une seconde zone de la carte de circuit imprimé, le circuit codec audio comprenant une borne d'entrée de signal et une seconde borne de mise à la terre électriquement connectée à la seconde partie de mise à la terre; et un connecteur connecté électriquement à la borne d'entrée, le connecteur comprenant une première broche qui peut être connectée électriquement à une borne de signal d'un microphone inclus dans un dispositif électronique externe et une seconde broche qui peut être connectée électriquement à une borne de mise à la terre du microphone, la seconde broche pouvant être connectée électriquement à la seconde partie de mise à la terre. Divers autres modes de réalisation de la présente invention sont également possibles.

(KO): 본 발명의 다양한 실시예들은, 제1 접지부 및 제2 접지부를 포함하는 회로 기판; 상기 제1 접지부와 전기적으로 연결된 제1 접지 단자를 포함하고, 상기 회로 기판의 제1 영역에 배치된 무선 통신 회로; 상기 제2 접지부와 전기적으로 연결된 제2 접지 단자 및 신호의 입력 단자를 포함하고, 상기 회로 기판의 제2 영역에 배치된 오디오 코덱 회로; 및 상기 입력 단자와 전기적으로 연결되고, 외부 전자 장치에 포함된 마이크론의 신호 단자와 전기적으로 연결될 수 있는 제1 핀, 및 상기 마이크론의 접지 단자와 전기적으로 연결될 수 있는 제2 핀을 포함하는 커넥터를 포함하고, 상기 제2 핀은 상기 제2 접지부와 전기적으로 연결될 수 있다. 또한, 본 발명의 다양한 실시예들은 다른 실시예들이 가능할 수 있다.

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